

Abstract**METHOD FOR PLATING AND PLATING SOLUTION THEREFOR**

5 A solution is described, in particular for electroless deposition of a metal on a polyimide substrate. The solution from which the metal is deposited, comprises a source of metal ions; a reducing agent; an additive to adjust the pH of said bath to a predetermined value; and an aromatic sulfonic acid. The solution is used in a method for electroless deposition of a metal onto a substrate wherein the substrate preferably
10 comprises polyimide exposed at a surface thereof. The method of the present invention provides a metal layer which shows good adhesion towards the polyimide substrate and which is very smooth and does not need any additional smoothing treatment.

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